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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c712-20i-ss

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PIC16C712/716

FIGURE 3-1: BLOCK DIAGRAM OF RA3:RA0

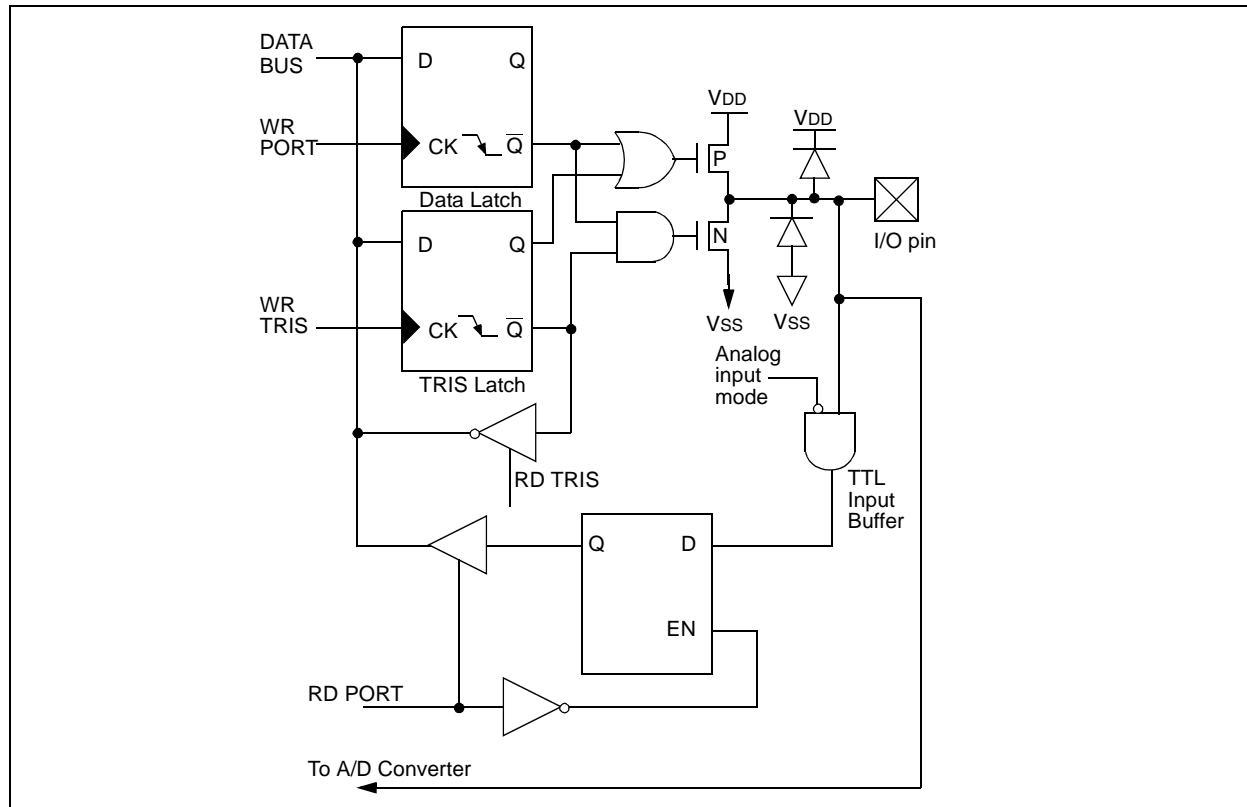
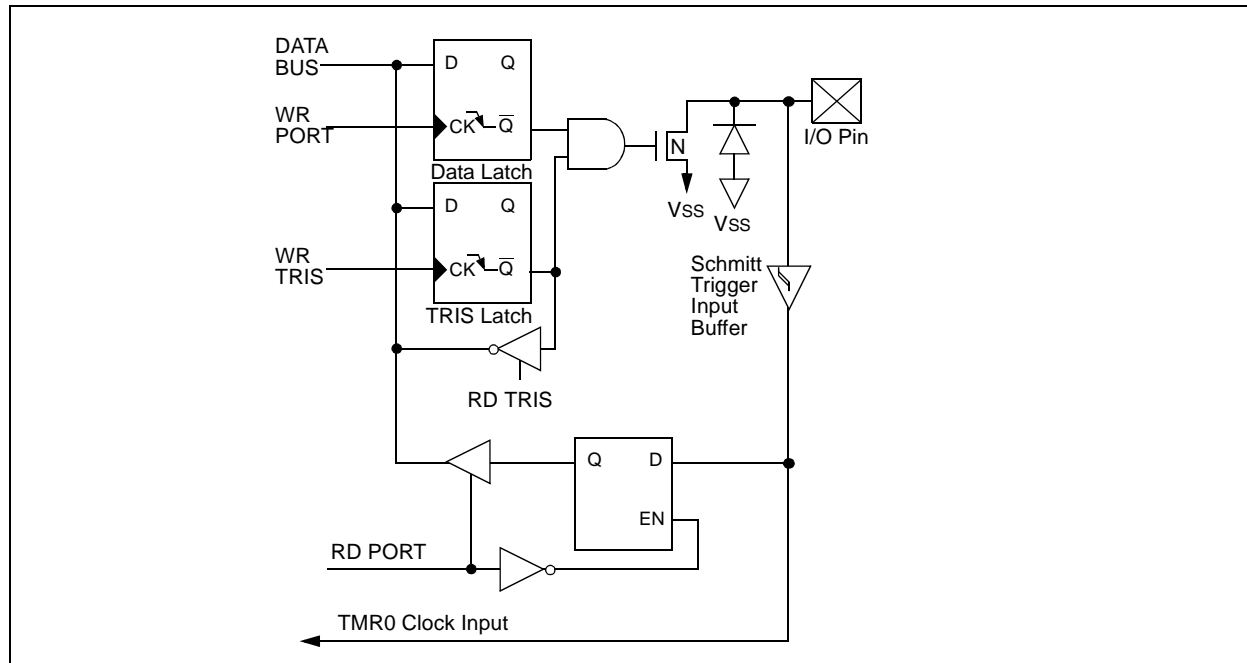


FIGURE 3-2: BLOCK DIAGRAM OF RA4/T0CKI PIN



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4.2.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control (i.e., it can be changed “on the fly” during program execution).

Note: To avoid an unintended device Reset, a specific instruction sequence (shown in the PIC® Mid-Range Reference Manual, DS33023) must be executed when changing the prescaler assignment from Timer0 to the WDT. This sequence must be followed even if the WDT is disabled.

4.3 Timer0 Interrupt

The TMR0 interrupt is generated when the TMR0 register overflows from FFh to 00h. This overflow sets bit T0IF (INTCON<2>). The interrupt can be masked by clearing bit T0IE (INTCON<5>). Bit T0IF must be cleared in software by the Timer0 module Interrupt Service Routine before re-enabling this interrupt. The TMR0 interrupt cannot awaken the processor from Sleep since the timer is shut off during Sleep.

FIGURE 4-2: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER

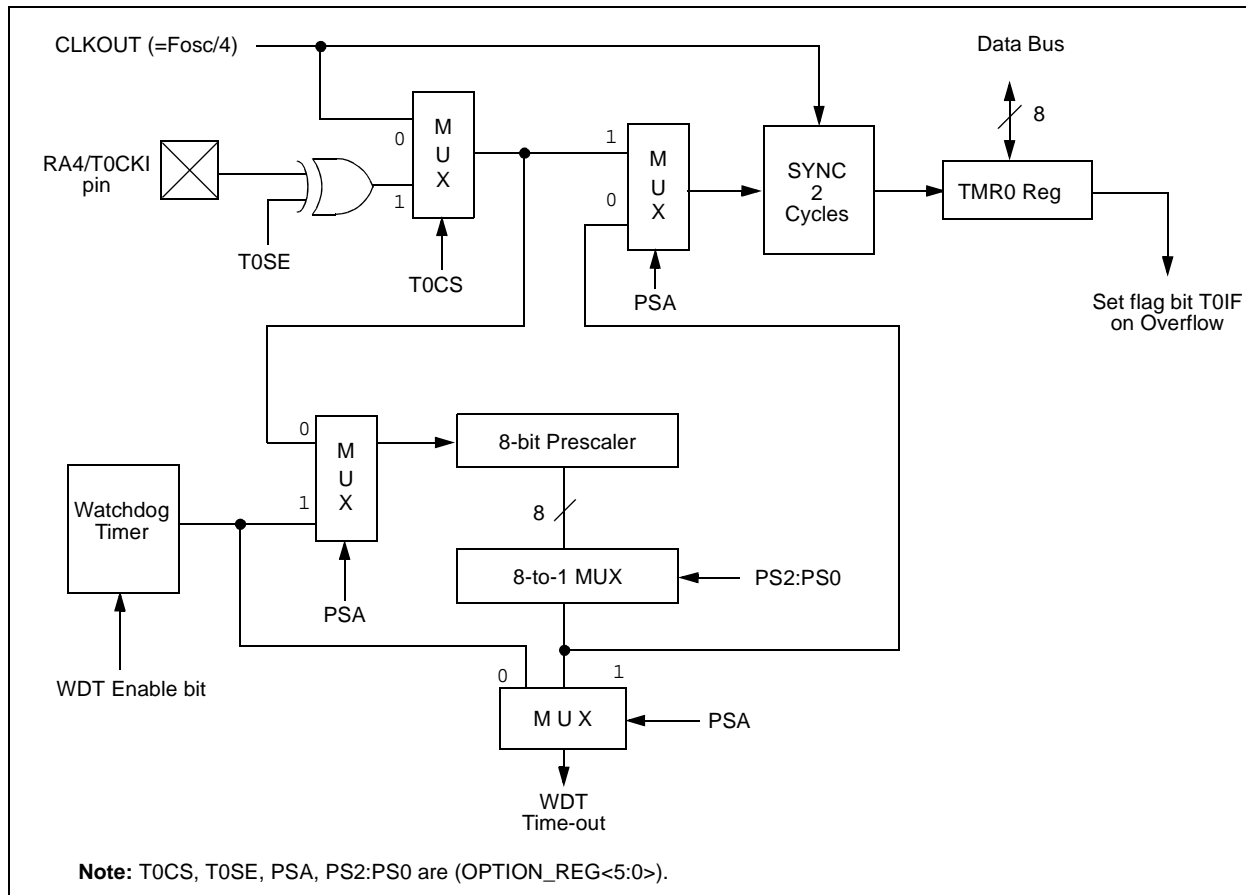


TABLE 4-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
01h	TMR0	Timer0 Module's Register								xxxx xxxx	uuuu uuuu
0Bh,8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
81h	OPTION_REG	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	—	—	— ⁽¹⁾	Bit 4	PORTA Data Direction Register				--11 1111	--11 1111

Legend: x = unknown, u = unchanged, — = unimplemented locations read as '0'. Shaded cells are not used by Timer0.

Note 1: Reserved bit; Do Not Use.

5.0 TIMER1 MODULE

The Timer1 module timer/counter has the following features:

- 16-bit timer/counter
(Two 8-bit registers; TMR1H and TMR1L)
- Readable and writable (Both registers)
- Internal or external clock select
- Interrupt on overflow from FFFFh to 0000h
- Reset from CCP module trigger

Timer1 has a control register, shown in Figure 5-1. Timer1 can be enabled/disabled by setting/clearing control bit TMR1ON (T1CON<0>).

Figure 5-2 is a simplified block diagram of the Timer1 module.

Additional information on timer modules is available in the PIC® Mid-Range Reference Manual, (DS33023).

5.1 Timer1 Operation

Timer1 can operate in one of these modes:

- As a timer
- As a synchronous counter
- As an asynchronous counter

The operating mode is determined by the clock select bit, TMR1CS (T1CON<1>).

In timer mode, Timer1 increments every instruction cycle. In counter mode, it increments on every rising edge of the external clock input.

When the Timer1 oscillator is enabled (T1OSCEN is set), the RB2/T1OSI and RB1/T1OSO/T1CKI pins become inputs. That is, the TRISB<2:1> value is ignored.

Timer1 also has an internal "Reset input". This Reset can be generated by the CCP module (see **Section 7.0 "Capture/Compare/PWM (CCP) Module(s)"**).

FIGURE 5-1: T1CON: TIMER1 CONTROL REGISTER (ADDRESS 10h)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR1ON
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
-n = Value at POR Reset

bit 7-6: **Unimplemented:** Read as '0'

bit 5-4: **T1CKPS1:T1CKPS0:** Timer1 Input Clock Prescale Select bits

11 = 1:8 Prescale value
10 = 1:4 Prescale value
01 = 1:2 Prescale value
00 = 1:1 Prescale value

bit 3: **T1OSCEN:** Timer1 Oscillator Enable Control bit

1 = Oscillator is enabled
0 = Oscillator is shut off
Note: The oscillator inverter and feedback resistor are turned off to eliminate power drain

bit 2: **T1SYNC:** Timer1 External Clock Input Synchronization Control bit

TMR1CS = 1
1 = Do not synchronize external clock input
0 = Synchronize external clock input

TMR1CS = 0
This bit is ignored. Timer1 uses the internal clock when TMR1CS = 0.

bit 1: **TMR1CS:** Timer1 Clock Source Select bit

1 = External clock from pin RB1/T1OSO/T1CKI (on the rising edge)
0 = Internal clock (Fosc/4)

bit 0: **TMR1ON:** Timer1 On bit

1 = Enables Timer1
0 = Stops Timer1

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6.0 TIMER2 MODULE

The Timer2 module timer has the following features:

- 8-bit timer (TMR2 register)
- 8-bit period register (PR2)
- Readable and writable (both registers)
- Software programmable prescaler (1:1, 1:4, 1:16)
- Software programmable postscaler (1:1 to 1:16)
- Interrupt on TMR2 match of PR2

Timer2 has a control register, shown in Figure 6-1. Timer2 can be shut off by clearing control bit TMR2ON (T2CON<2>) to minimize power consumption.

Figure 6-2 is a simplified block diagram of the Timer2 module.

Additional information on timer modules is available in the PIC® Mid-Range Reference Manual, (DS33023).

FIGURE 6-1: T2CON: TIMER2 CONTROL REGISTER (ADDRESS 12h)

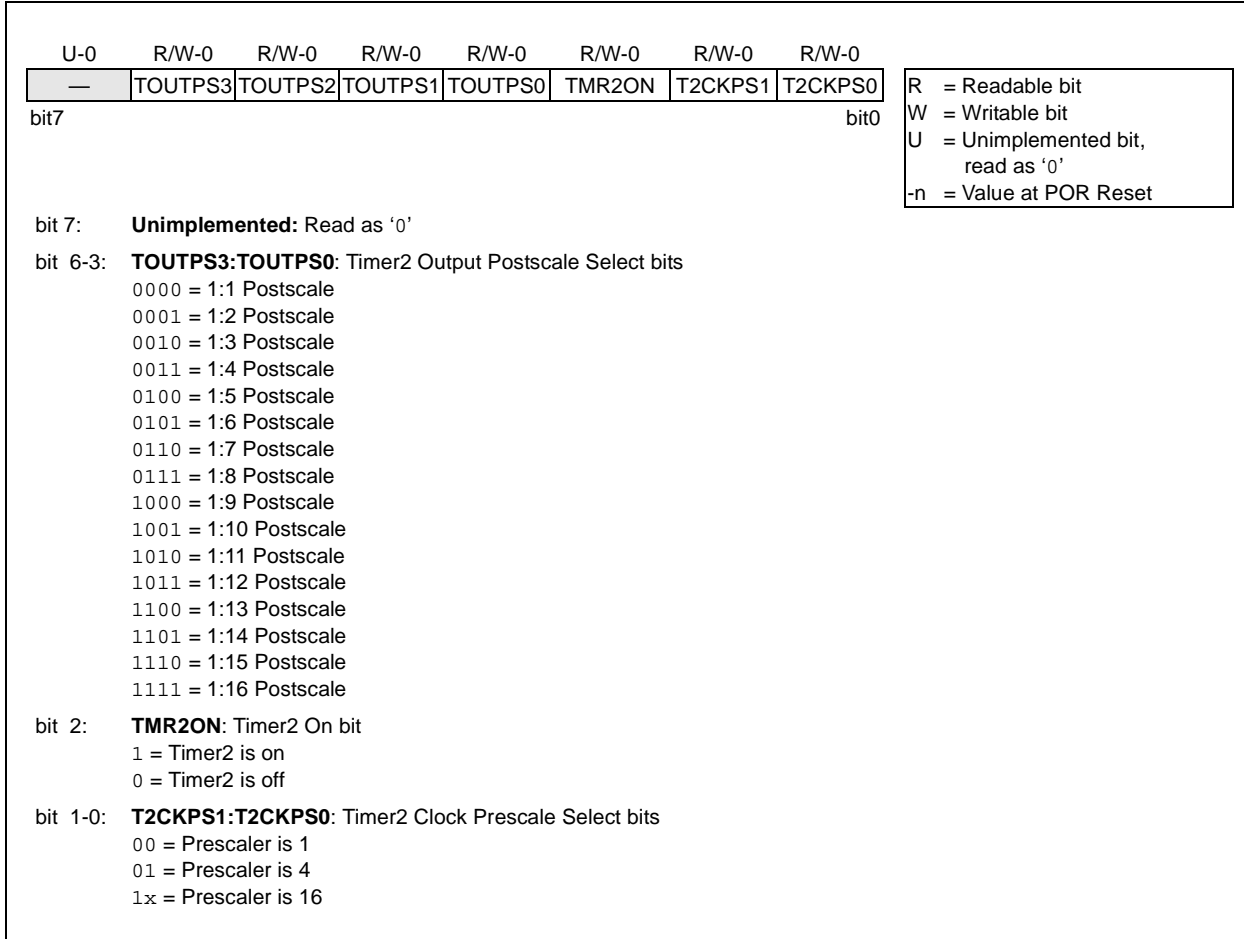
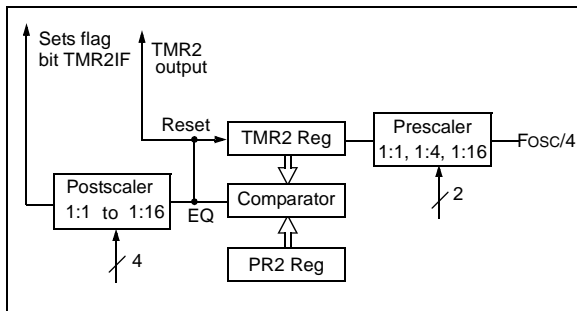


FIGURE 6-2: TIMER2 BLOCK DIAGRAM



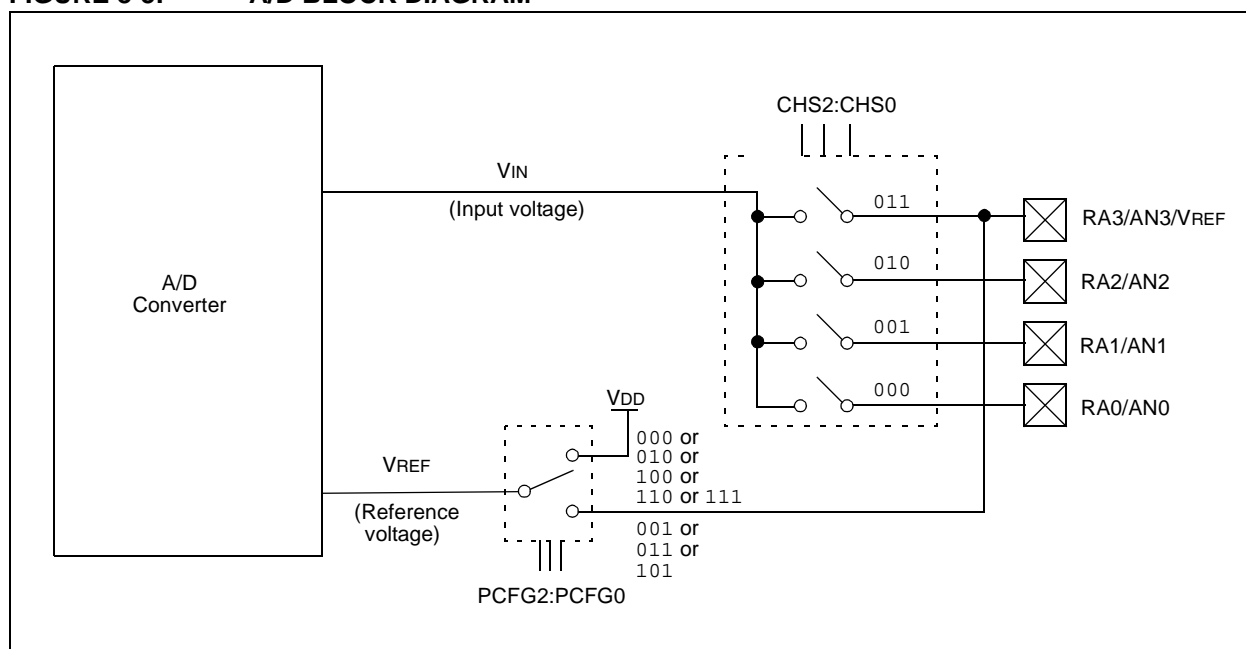
The ADRES register contains the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the ADRES register, the $\overline{\text{GO/DONE}}$ bit (ADCON0<2>) is cleared and the A/D Interrupt Flag bit ADIF is set. The block diagram of the A/D module is shown in Figure 8-3.

The value that is in the ADRES register is not modified for a Power-on Reset. The ADRES register will contain unknown data after a Power-on Reset.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as an input. To determine acquisition time, see **Section 8.1 “A/D Acquisition Requirements”**. After this acquisition time has elapsed, the A/D conversion can be started. The following steps should be followed for doing an A/D conversion:

1. Configure the A/D module:
 - Configure analog pins/voltage reference/ and digital I/O (ADCON1)
 - Select A/D input channel (ADCON0)
 - Select A/D conversion clock (ADCON0)
 - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if desired):
 - Clear ADIF bit
 - Set ADIE bit
 - Set GIE bit
3. Wait the required acquisition time.
4. Start conversion:
 - Set $\overline{\text{GO/DONE}}$ bit (ADCON0)
5. Wait for A/D conversion to complete, by either:
 - Polling for the $\overline{\text{GO/DONE}}$ bit to be cleared
 OR
 - Waiting for the A/D interrupt
6. Read A/D Result register (ADRES), clear bit ADIF if required.
7. For the next conversion, go to step 1 or step 2 as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 2TAD is required before next acquisition starts.

FIGURE 8-3: A/D BLOCK DIAGRAM



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8.4 A/D Conversions

Note: The GO/DONE bit should **NOT** be set in the same instruction that turns on the A/D.

8.5 Use of the CCP Trigger

An A/D conversion can be started by the “Special Event Trigger” of the CCP1 module. This requires that the CCP1M3:CCP1M0 bits (CCP1CON<3:0>) be programmed as 1011 and that the A/D module is enabled (ADON bit is set). When the trigger occurs, the

GO/DONE bit will be set, starting the A/D conversion, and the Timer1 counter will be reset to zero. Timer1 is reset to automatically repeat the A/D acquisition period with minimal software overhead (moving the ADRES to the desired location). The appropriate analog input channel must be selected and the minimum acquisition done before the “Special Event Trigger” sets the GO/DONE bit (starts a conversion).

If the A/D module is not enabled (ADON is cleared), then the “Special Event Trigger” will be ignored by the A/D module, but will still reset the Timer1 counter.

TABLE 8-2: SUMMARY OF A/D REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
05h	PORTA	—	—	— ⁽¹⁾	RA4	RA3	RA2	RA1	RA0	--xx xxxx	--xu uuuu
0Bh,8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF	—	—	—	CCP1IF	TMR2IF	TMR1IF	-0-- -000	-0-- -000
1Eh	ADRES	A/D Result Register								xxxx xxxx	uuuu uuuu
1Fh	ADCON0	ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/DONE	—	ADON	0000 00-0	0000 00-0
85h	TRISA	—	—	— ⁽¹⁾	PORTA Data Direction Register					---1 1111	---1 1111
8Ch	PIE1	—	ADIE	—	—	—	CCP1IE	TMR2IE	TMR1IE	-0-- -000	-0-- 0000
9Fh	ADCON1	—	—	—	—	—	PCFG2	PCFG1	PCFG0	---- -000	---- -000

Legend: x = unknown, u = unchanged, — = unimplemented read as ‘0’. Shaded cells are not used for A/D conversion.

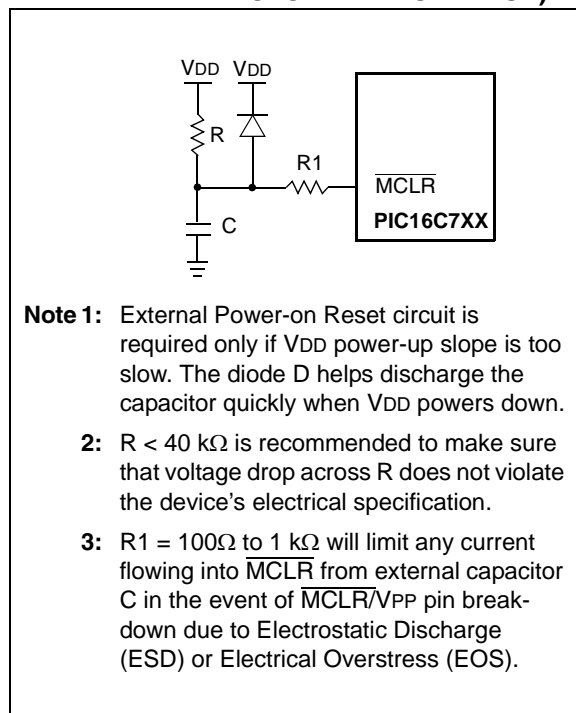
Note 1: Reserved bits; Do Not Use.

9.4 Power-On Reset (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected (to a level of 1.5V-2.1V). To take advantage of the POR, just tie the $\overline{\text{MCLR}}$ pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for VDD is specified (parameter D004). For a slow rise time, see Figure 9-5.

When the device starts normal operation (exits the Reset condition), device operating parameters (voltage, frequency, temperature,...) must be met to ensure operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met. Brown-out Reset may be used to meet the start-up conditions.

FIGURE 9-5: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



9.5 Power-up Timer (PWRT)

The Power-up Timer provides a fixed nominal time-out (parameter #33), on power-up only, from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in Reset as long as the PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A Configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip to chip due to VDD, temperature, and process variation. See DC parameters for details.

9.6 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over (parameter #32). This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from Sleep.

9.7 Brown-Out Reset (BOR)

The PIC16C712/716 members have on-chip Brown-out Reset circuitry. A Configuration bit, BODEN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below 4.0V, refer to VBOR parameter D005(VBOR) for a time greater than parameter (TBOR) in Table 12-6. The brown-out situation will reset the chip. A Reset is not guaranteed to occur if VDD falls below 4.0V for less than parameter (TBOR).

On any Reset (Power-on, Brown-out, Watchdog, etc.) the chip will remain in Reset until VDD rises above VBOR. The Power-up Timer will now be invoked and will keep the chip in Reset an additional 72 ms.

If VDD drops below VBOR while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be re-initialized. Once VDD rises above VBOR, the Power-Up Timer will execute a 72 ms Reset. The Power-up Timer should always be enabled when Brown-out Reset is enabled. Figure 9-7 shows typical Brown-out situations.

For operations where the desired brown-out voltage is other than 4V, an external brown-out circuit must be used. Figure 9-8, 9-9 and 9-10 show examples of external brown-out protection circuits.

When the `SLEEP` instruction is being executed, the next instruction (`PC + 1`) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the `GIE` bit. If the `GIE` bit is clear (disabled), the device continues execution at the instruction after the `SLEEP` instruction. If the `GIE` bit is set (enabled), the device executes the instruction after the `SLEEP` instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following `SLEEP` is not desirable, the user should have a `NOP` after the `SLEEP` instruction.

9.13.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (`GIE` cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a `SLEEP` instruction, the `SLEEP` instruction will complete as a `NOP`. Therefore, the `WDT` and `WDT`

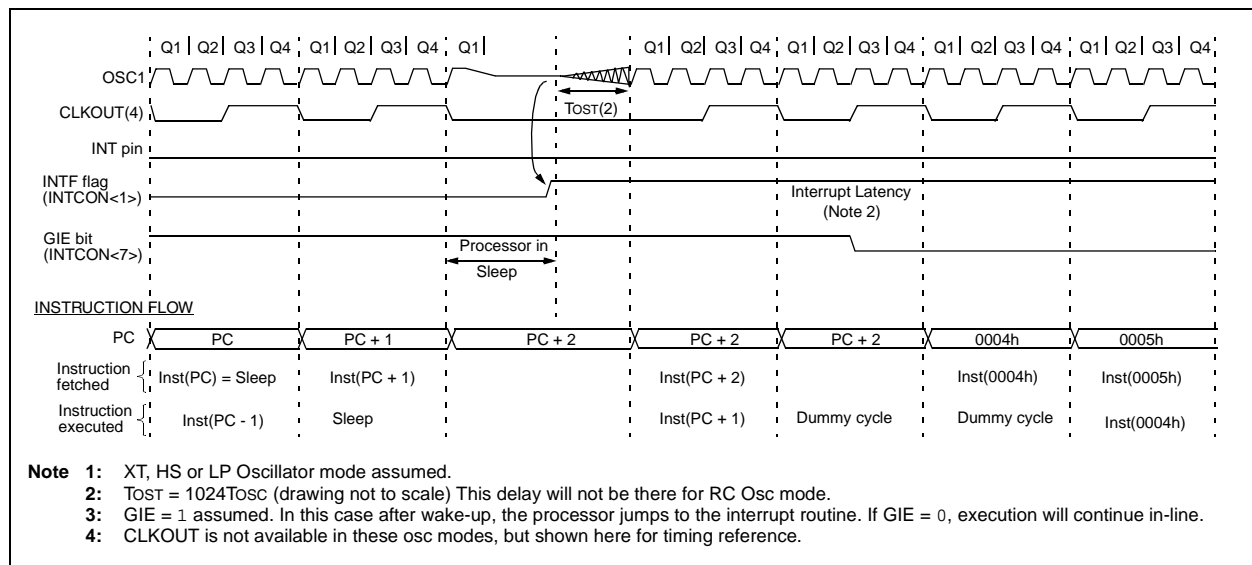
postscaler will not be cleared, the `TO` bit will not be set and `PD` bits will not be cleared.

- If the interrupt occurs **during or after** the execution of a `SLEEP` instruction, the device will immediately wake-up from Sleep. The `SLEEP` instruction will be completely executed before the wake-up. Therefore, the `WDT` and `WDT` postscaler will be cleared, the `TO` bit will be set and the `PD` bit will be cleared.

Even if the flag bits were checked before executing a `SLEEP` instruction, it may be possible for flag bits to become set before the `SLEEP` instruction completes. To determine whether a `SLEEP` instruction executed, test the `PD` bit. If the `PD` bit is set, the `SLEEP` instruction was executed as a `NOP`.

To ensure that the `WDT` is cleared, a `CLRWDT` instruction should be executed before a `SLEEP` instruction.

FIGURE 9-17: WAKE-UP FROM SLEEP THROUGH INTERRUPT



9.14 Program Verification/Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

Note: Microchip does not recommend code protecting windowed devices.

9.15 ID Locations

Four memory locations (2000h-2003h) are designated as ID locations where the user can store checksum or other code-identification numbers. These locations are not accessible during normal execution, but are readable and writable during Program/Verify. It is recommended that only the 4 Least Significant bits of the ID location are used.

For ROM devices, these values are submitted along with the ROM code.

9.16 In-Circuit Serial Programming™

PIC16CXXX microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

For complete details on serial programming, please refer to the In-Circuit Serial Programming™ (ICSP™) Guide, (DS30277).

11.2 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for all PIC MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

11.3 MPLAB C18 and MPLAB C30 C Compilers

The MPLAB C18 and MPLAB C30 Code Development Systems are complete ANSI C compilers for Microchip's PIC18 family of microcontrollers and dsPIC30F family of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use not found with other compilers.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

11.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

11.5 MPLAB ASM30 Assembler, Linker and Librarian

MPLAB ASM30 Assembler produces relocatable machine code from symbolic assembly language for dsPIC30F devices. MPLAB C30 C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire dsPIC30F instruction set
- Support for fixed-point and floating-point data
- Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

11.6 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, as well as internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C18 and MPLAB C30 C Compilers, and the MPASM and MPLAB ASM30 Assemblers. The software simulator offers the flexibility to develop and debug code outside of the laboratory environment, making it an excellent, economical software development tool.

11.7 MPLAB ICE 2000 High-Performance In-Circuit Emulator

The MPLAB ICE 2000 In-Circuit Emulator is intended to provide the product development engineer with a complete microcontroller design tool set for PIC microcontrollers. Software control of the MPLAB ICE 2000 In-Circuit Emulator is advanced by the MPLAB Integrated Development Environment, which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICE 2000 is a full-featured emulator system with enhanced trace, trigger and data monitoring features. Interchangeable processor modules allow the system to be easily reconfigured for emulation of different processors. The architecture of the MPLAB ICE 2000 In-Circuit Emulator allows expansion to support new PIC microcontrollers.

The MPLAB ICE 2000 In-Circuit Emulator system has been designed as a real-time emulation system with advanced features that are typically found on more expensive development tools. The PC platform and Microsoft® Windows® 32-bit operating system were chosen to best make these features available in a simple, unified application.

11.8 MPLAB ICE 4000 High-Performance In-Circuit Emulator

The MPLAB ICE 4000 In-Circuit Emulator is intended to provide the product development engineer with a complete microcontroller design tool set for high-end PIC MCUs and dsPIC DSCs. Software control of the MPLAB ICE 4000 In-Circuit Emulator is provided by the MPLAB Integrated Development Environment, which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICE 4000 is a premium emulator system, providing the features of MPLAB ICE 2000, but with increased emulation memory and high-speed performance for dsPIC30F and PIC18XXXX devices. Its advanced emulator features include complex triggering and timing, and up to 2 Mb of emulation memory.

The MPLAB ICE 4000 In-Circuit Emulator system has been designed as a real-time emulation system with advanced features that are typically found on more expensive development tools. The PC platform and Microsoft Windows 32-bit operating system were chosen to best make these features available in a simple, unified application.

11.9 MPLAB ICD 2 In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD 2, is a powerful, low-cost, run-time development tool, connecting to the host PC via an RS-232 or high-speed USB interface. This tool is based on the Flash PIC MCUs and can be used to develop for these and other PIC MCUs and dsPIC DSCs. The MPLAB ICD 2 utilizes the in-circuit debugging capability built into the Flash devices. This feature, along with Microchip's In-Circuit Serial Programming™ (ICSP™) protocol, offers cost-effective, in-circuit Flash debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by setting breakpoints, single stepping and watching variables, and CPU status and peripheral registers. Running at full speed enables testing hardware and applications in real time. MPLAB ICD 2 also serves as a development programmer for selected PIC devices.

11.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at VDDMIN and VDDMAX for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages and a modular, detachable socket assembly to support various package types. The ICSP™ cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices and incorporates an SD/MMC card for file storage and secure data applications.

PIC16C712/716

FIGURE 12-1: PIC16C712/716 VOLTAGE-FREQUENCY GRAPH, $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$

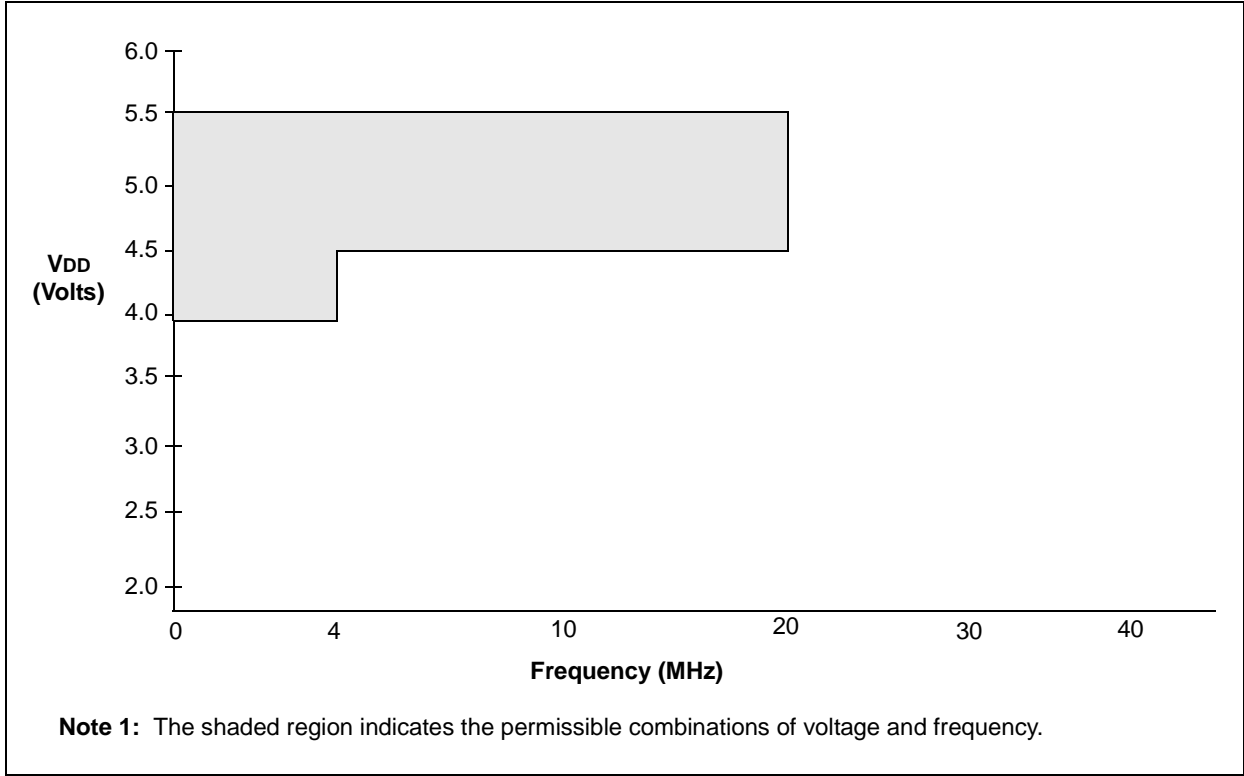
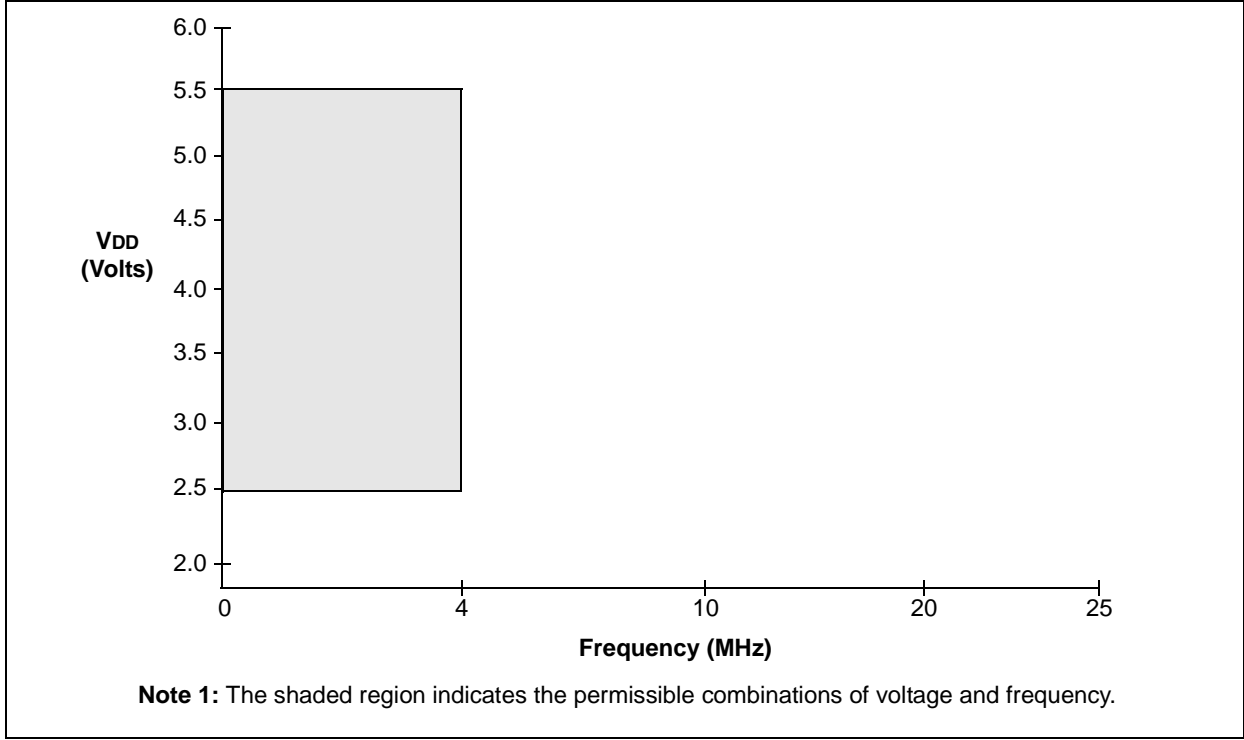


FIGURE 12-2: PIC16LC712/716 VOLTAGE-FREQUENCY GRAPH, $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$



PIC16C712/716

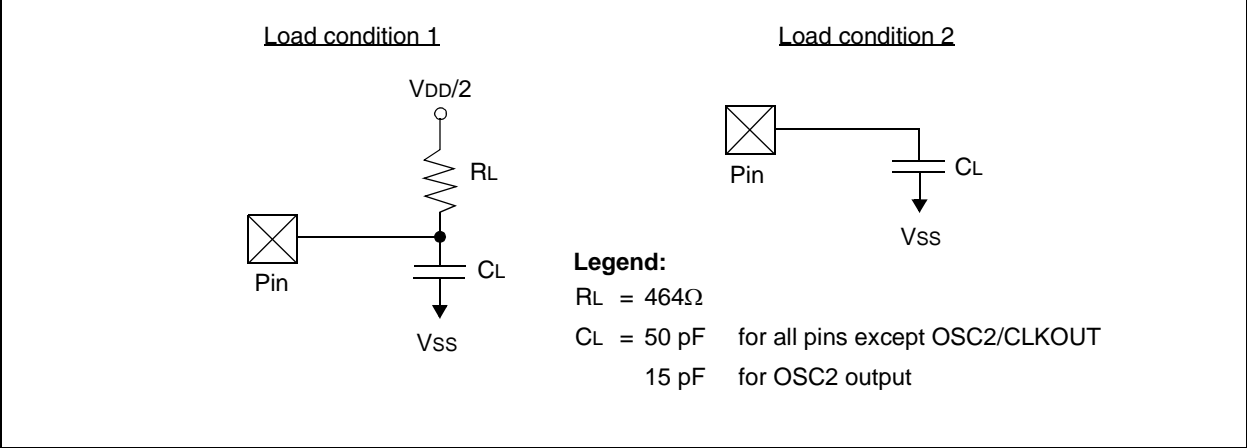
12.4.2 TIMING CONDITIONS

The temperature and voltages specified in Table 12-1 apply to all timing specifications, unless otherwise noted. Figure 12-3 specifies the load conditions for the timing specifications.

TABLE 12-1: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	Standard Operating Conditions (unless otherwise stated)	
	Operating temperature	$0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial
		$-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial
		$-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended
	Operating voltage V_{DD} range as described in DC spec Section 12.1 “DC Characteristics: PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712/716-20 (Commercial, Industrial, Extended)” and Section 12.2 “DC Characteristics: PIC16LC712/716-04 (Commercial, Industrial)” .	
	LC parts operate for commercial/industrial temp's only.	

FIGURE 12-3: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



12.4.3 TIMING DIAGRAMS AND SPECIFICATIONS

FIGURE 12-4: EXTERNAL CLOCK TIMING

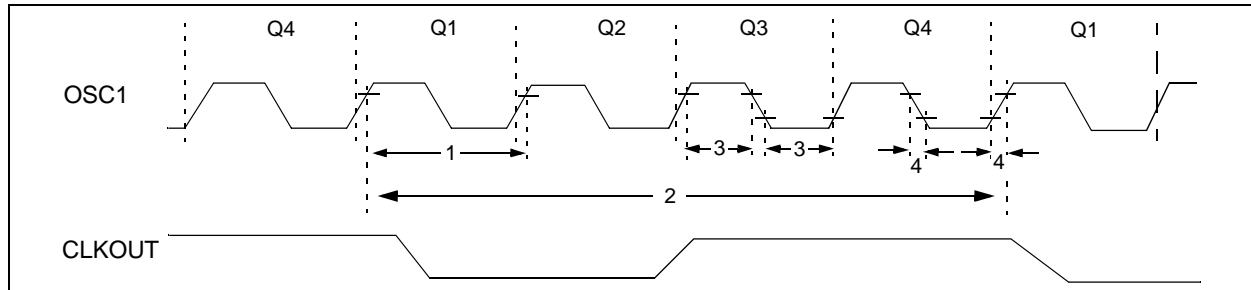


TABLE 12-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
1A	Fosc	External CLKIN Frequency (Note 1)	DC	—	4	MHz	RC and XT osc modes
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
1	Tosc	External CLKIN Period (Note 1)	250	—	—	ns	RC and XT osc modes
			250	—	—	ns	HS osc mode (-04)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			50	—	250	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
2	Tcy	Instruction Cycle Time (Note 1)	200	—	DC	ns	Tcy = 4/Fosc
3*	TosL, TosH	External Clock in (OSC1) High or Low Time	100	—	—	ns	XT oscillator
			2.5	—	—	μs	LP oscillator
			15	—	—	ns	HS oscillator
4*	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note1: Instruction cycle period (Tcy) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin.

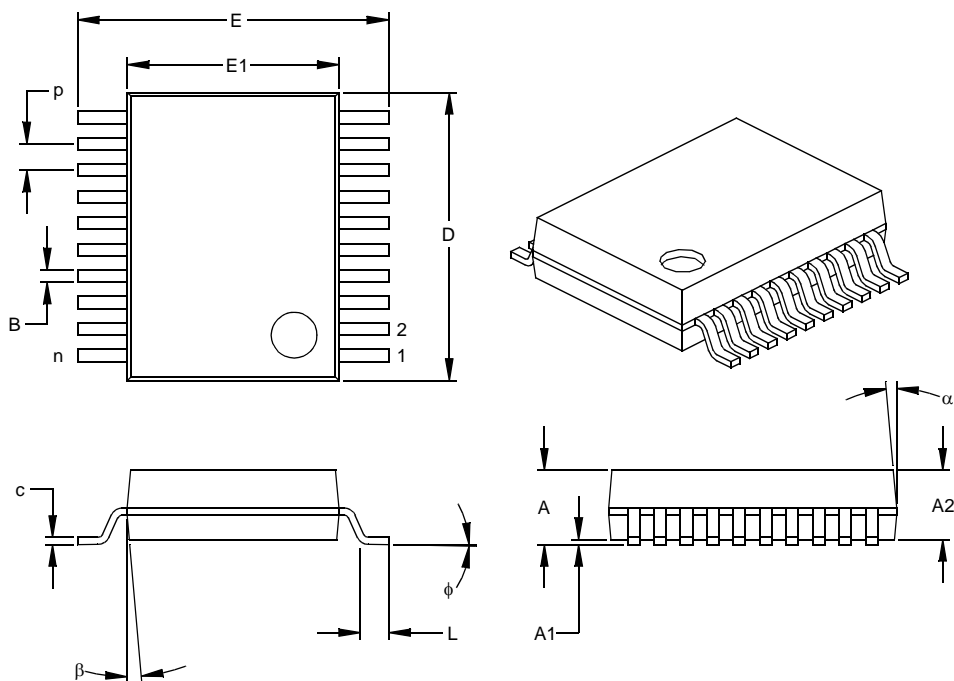
When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

PIC16C712/716

NOTES:

20-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	φ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-150

Drawing No. C04-072

APPENDIX A: REVISION HISTORY

Version	Date	Revision Description
A	2/99	This is a new data sheet. However, the devices described in this data sheet are the upgrades to the devices found in the <i>PIC16C6X Data Sheet</i> , DS30234, and the <i>PIC16C7X Data Sheet</i> , DS30390.
B	9/05	Removed Preliminary Status.
C	1/13	Added a note to each package outline drawing.

APPENDIX B: CONVERSION CONSIDERATIONS

There are no previous versions of this device.

APPENDIX C: MIGRATION FROM BASE-LINE TO MID-RANGE DEVICES

This section discusses how to migrate from a baseline device (i.e., PIC16C5X) to a mid-range device (i.e., PIC16CXXX).

The following are the list of modifications over the PIC16C5X microcontroller family:

1. Instruction word length is increased to 14-bits. This allows larger page sizes both in program memory (2K now as opposed to 512 before) and register file (128 bytes now versus 32 bytes before).
2. A PC high latch register (PCLATH) is added to handle program memory paging. Bits PA2, PA1, PA0 are removed from STATUS register.
3. Data memory paging is redefined slightly. STATUS register is modified.
4. Four new instructions have been added: RETURN, RETFIE, ADDLW, and SUBLW. Two instructions TRIS and OPTION are being phased out although they are kept for compatibility with PIC16C5X.
5. OPTION_REG and TRIS registers are made addressable.
6. Interrupt capability is added. Interrupt vector is at 0004h.
7. Stack size is increased to 8 deep.
8. Reset vector is changed to 0000h.
9. Reset of all registers is revisited. Five different Reset (and wake-up) types are recognized. Registers are reset differently.
10. Wake-up from Sleep through interrupt is added.

11. Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT) are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
12. PORTB has weak pull-ups and interrupt on change feature.
13. T0CKI pin is also a port pin (RA4) now.
14. FSR is made a full eight-bit register.
15. "In-circuit serial programming" is made possible. The user can program PIC16CXX devices using only five pins: VDD, VSS, MCLR/VPP, RB6 (clock) and RB7 (data in/out).
16. PCON STATUS register is added with a Power-on Reset Status bit (POR).
17. Code protection scheme is enhanced such that portions of the program memory can be protected, while the remainder is unprotected.
18. Brown-out protection circuitry has been added. Controlled by Configuration Word bit BODEN. Brown-out Reset ensures the device is placed in a Reset condition if VDD dips below a fixed setpoint.

To convert code written for PIC16C5X to PIC16CXXX, the user should take the following steps:

1. Remove any program memory page select operations (PA2, PA1, PA0 bits) for CALL, GOTO.
2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
5. Change Reset vector to 0000h.

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